

**PART INFORMATION**

Mfg Item Number	MC68EC040FE33A
Mfg Item Name	CQUAD 184

**SUPPLIER**

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2017-06-22
Response Document ID	8061K00062D001A1.12
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
Contact Phone	1-800-521-6274
Contact Email	support@freescale.com
Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

**DECLARATION**

EU RoHS	Yes
Pb Free	No
HalogenFree	Yes
Plating Indicator	e3
EU RoHS Exemption(s)	7c-l

**MANUFACTURING**

Mfg Item Number	MC68EC040FE33A
Mfg Item Name	CQUAD 184
Version	ALL
Weight	10.566950
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	1
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

<b>RoHS</b>	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
Exemptions in this part	7c-I:Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Epoxy Die Attach	0.0624				7c-1		g				
Epoxy Die Attach		Lead/Lead Compounds	Lead (II) oxide	1317-36-8		0.00128925	g	20661	2.0661	122	0.0122
Epoxy Die Attach		Solvents, additives, and other materials	Other organic Silicon Compounds	-		0.00515705	g	82645	8.2645	488	0.0488
Epoxy Die Attach		Metals	Silver, metal	7440-22-4		0.05157029	g	826447	82.6447	4880	0.488
Epoxy Die Attach		Metals	Silver (I) oxide	20667-12-3		0.00257849	g	41322	4.1322	244	0.0244
Epoxy Die Attach		Metals	Tellurium in Glass frnt	7446-07-3		0.00051567	g	8264	0.8264	48	0.0048
Epoxy Die Attach		Metals	Vanadium (V) oxide	1314-62-1		0.00128925	g	20661	2.0661	122	0.0122
Bonding Wire, Aluminum	0.0019						g				
Bonding Wire, Aluminum		Metals	Aluminum, metal	7429-90-5		0.0019	g	1000000	100	179	0.0179
Cap/Cover	4.2256				7c-1		g				
Cap/Cover		Metals	Aluminum Oxides (Al2O3)	1344-28-1		3.31063083	g	783470	78.347	313300	31.33
Cap/Cover		Metals	Boron oxide	1303-86-2		0.03361887	g	7956	0.7956	3181	0.3181
Cap/Cover		Lead/Lead Compounds	Lead (II) oxide	1317-36-8		0.28575197	g	67624	6.7624	27042	2.7042
Cap/Cover		Glass	Silicon dioxide	7631-86-9		0.00560315	g	1326	0.1326	530	0.053
Cap/Cover		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.09235471	g	21856	2.1856	8739	0.8739
Cap/Cover		Metals	Other titanium compounds	-		0.09273079	g	21945	2.1945	8775	0.8775
Cap/Cover		Metals	Zinc oxide	1314-13-2		0.00560315	g	1326	0.1326	530	0.053
Cap/Cover		Metals	Other zinc compounds	-		0.17565397	g	41569	4.1569	16622	1.6622
Cap/Cover		Metals	Manganese oxide	1344-43-0		0.08245836	g	19514	1.9514	7803	0.7803
Cap/Cover		Pigments and Dyes	C.I. Pigment Black 27	68186-97-0		0.00280157	g	663	0.0663	265	0.0265
Cap/Cover		Metals	Tin zinc oxide (SnZnO3)	12036-37-2		0.13839263	g	32751	3.2751	13096	1.3096
Lead Frame	6.1188				7c-1		g				
Lead Frame		Metals	Aluminum, metal	7429-90-5		0.00474819	g	776	0.0776	449	0.0449
Lead Frame		Metals	Aluminum Oxides (Al2O3)	1344-28-1		3.42996678	g	560562	56.0562	324610	32.461
Lead Frame		Metals	Boron oxide	1303-86-2		0.06246683	g	10209	1.0209	5911	0.5911
Lead Frame		Metals	Iron, metal	7439-89-6		0.74285291	g	121405	12.1405	70299	7.0299
Lead Frame		Metals	Other iron compounds	-		0.09595502	g	15682	1.5682	9080	0.908
Lead Frame		Lead/Lead Compounds	Lead (II) oxide	1317-36-8		0.53081814	g	86752	8.6752	50233	5.0233
Lead Frame		Nickel (external applications only)	Nickel	7440-02-0		0.53079713	g	87922	8.7922	50911	5.0911
Lead Frame		Glass	Silicon dioxide	7631-86-9		0.0104142	g	1702	0.1702	985	0.0985
Lead Frame		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.09555118	g	15616	1.5616	9042	0.9042
Lead Frame		Metals	Other titanium compounds	-		0.09595502	g	15682	1.5682	9080	0.908
Lead Frame		Metals	Zinc oxide	1314-13-2		0.0104142	g	1702	0.1702	985	0.0985
Lead Frame		Metals	Other zinc compounds	-		0.15399796	g	25168	2.5168	14573	1.4573
Lead Frame		Metals	Manganese oxide	1344-43-0		0.08533278	g	13946	1.3946	8075	0.8075
Lead Frame		Pigments and Dyes	C.I. Pigment Black 27	68186-97-0		0.00523157	g	855	0.0855	495	0.0495
Lead Frame		Metals	Tin zinc oxide (SnZnO3)	12036-37-2		0.25711809	g	42021	4.2021	24332	2.4332
Silicon Semiconductor Die	0.12605						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.002521	g	20000	2	238	0.0238
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.123529	g	980000	98	11690	1.169
Lead Frame Plating	0.0322						g				
Lead Frame Plating		Lead/Lead Compounds	Lead	7439-92-1		0.00000644	g	200	0.02	0	0
Lead Frame Plating		Metals	Tin, metal	7440-31-5		0.03219356	g	999800	99.98	3046	0.3046

## LINKS

MCD LINK	
NXP website	<a href="http://www.nxp.com">http://www.nxp.com</a>
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf</a>
China RoHS	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY</a>
REACH signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf</a>
ELV signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf</a>
Conflict Minerals statement	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf</a>
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX</a>
FAQ	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ</a>
Technical Service Request	<a href="http://www.nxp.com/support/sales-and-support:SUPPORTHOME">http://www.nxp.com/support/sales-and-support:SUPPORTHOME</a>
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	<a href="http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf">http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf</a>

IPC1752 XML LINKS

[http://www.freescale.com/mcdfs/MC68EC040FE33A\\_IPC1752\\_v11.xml](http://www.freescale.com/mcdfs/MC68EC040FE33A_IPC1752_v11.xml)

[http://www.freescale.com/mcdfs/MC68EC040FE33A\\_IPC1752A.xml](http://www.freescale.com/mcdfs/MC68EC040FE33A_IPC1752A.xml)